



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32B226KOJNFNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22 µF, 16V, ±10%, X7R, 1210

## A. Samsung Part Number

<u>CL</u> <u>32</u> <u>B</u> <u>226</u> <u>K</u> <u>O</u> <u>J</u> <u>N</u> <u>F</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Seri	<b>es</b> Samsur	Samsung Multi-layer Ceramic Capacitor					
② Size	1210	(inch code) L	.: 3.2	± 0.3 mm	W:	$2.5 \pm 0.2$	mm
③ Diel	ectric X7R		8	Inner electrode	1	Ni	
④ Сар	acitance 22	μF		Termination	(	Cu	
⑤ Сар	acitance ±10	%		Plating	5	Sn 100%	(Pb Free)
tole	rance		9	Product	F	Product for P	OWER application
6 Rate	ed Voltage 16	V	10	Special	F	Reserved for	future use
7 Thio	ckness 2.5	± 0.2 mm	11)	Packaging	E	Embossed Ty	/pe, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition			
Capacitance	Within specified tolerance	120Hz±20% 0.5±0.1Vrms			
Tan δ (DF)	0.1 max.				
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.			
Resistance	Whichever is Smaller				
Appearance	No abnormal exterior appearance	Microscope (×10)			
Withstanding	No dielectric breakdown or	250% of the rated voltage			
Voltage	mechanical breakdown				
Temperature	X7R				
Characterisitcs	(From -55℃ to 125℃, Capacitance change shoud be within ±15%)				
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.			
of Termination	terminal electrode				
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (2mm)			
		with 1.0mm/sec.			
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder			
	is to be soldered newly	245±5℃, 3±0.3sec.			
		(preheating : 80~120°C for 10~30sec.)			
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.			
Soldering heat	Tan δ, IR : initial spec.				

	Performance	Test condition			
Vibration Test	Capacitance change: within ±5%	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours × 3 direction (x, y, z)			
Moisture	Capacitance change: within ±12.5%	With rated voltage			
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR: $12.5 \text{M}\Omega \cdot \mu \text{F}$ or Over				
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage			
Resistance	Tan δ: 0.125 max	Max. operating temperature			
	IR : 25MΩ·μF or Over				
		1000+48/-0hrs			
Temperature	Capacitance change: within ±7.5%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 °C			
		→ Max. operating temperature → 25°C			
		5 cycle test			

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.